Vantage Technology Receives New Purchase Order for Multiple SlurryScope™ Systems from Global Semiconductor Manufacturer

New multiple-system orders underscore high value of continuous, real-time analysis of undiluted slurry used during critical CMP process steps

CAMPBELL, CA – Nov. 1, 2012 – On the heels of winning a purchase order for multiple SlurryScope™ systems from a major Asian IC production fab, Vantage Technology today confirmed another multiple-system order from a world class semiconductor manufacturer with wafer fab operations spanning three continents.

"Demand for our metrology tool continues to grow," said Paul Magliocco, Vantage CEO. "Major wafer fabs are affirming the critical need to correlate continuous, real-time large particle counts (LPCs) in undiluted slurry with detrimental wafer micro-scratches caused during the chemical-mechanical planarization process." He noted that the need to monitor LPCs in the 1.0-to-10.0+ micron range has become increasingly critical as global chip makers step up their production of complex ICs at the 28nm node.

"The real-time data generated by our systems can be used to trigger corrective action when excursions are detected," added Magliocco. "By continuously monitoring slurry quality, optimizing filter life cycles and enabling timely corrective action, our customers can realize substantial cost savings." Vantage customers indicate that the slurry management experience gained at the 28nm node will be invaluable in supporting their drive to process wafers at 22nm and below.

About Vantage Technology

Operating from headquarters in Campbell, California, Vantage Technology Corporation was founded in 2010 by a cadre of Silicon Valley veterans with extensive experience in wafer fab production and test equipment. Focused on developing real-time micro-analytical metrology tools using advanced laser technology, proprietary algorithms and multicore image processing techniques, the company has targeted its first product at the semiconductor industry. Called the SlurryScope™ system, this real-time tool continuously detects large particles in undiluted slurry. Early detection of oversized particles enables timely corrective action that can minimize wafer micro-scratches and other defects caused by particle agglomeration during the chemical-mechanical planarization process. For more information, visit www.VantageTechCorp.com.

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Media Contact: Marty Mason, EVP, 408-866-8522, mmason@VantageTechCorp.com